
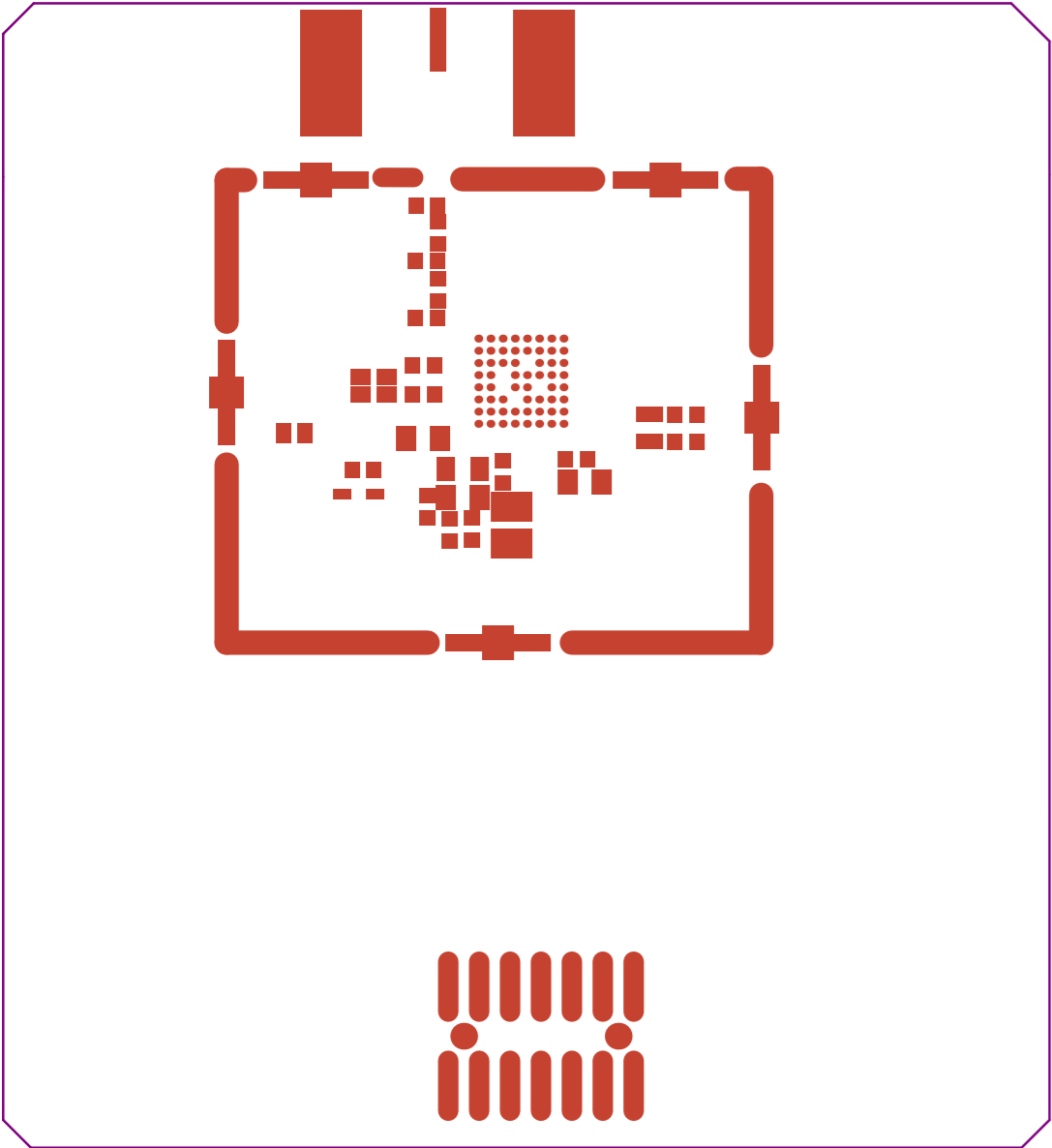

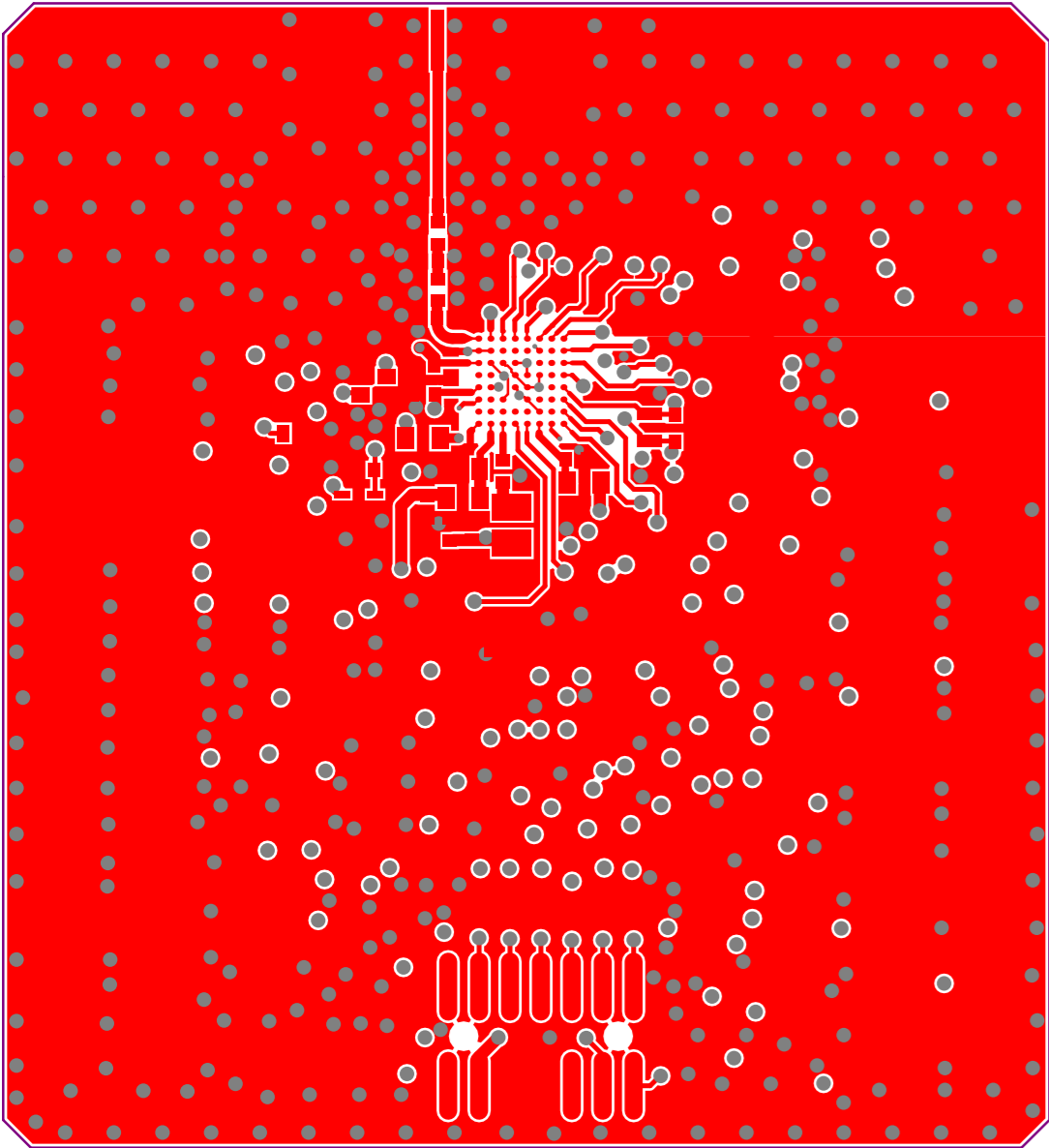



Project: MiniBoard_WBA55_BGA59_SMPS_SMA	
Layer: Top Overlay	Gerber: .GTO
Variant: [No Variations]	Ref: MB1807
Date: 15-Nov-2023	Rev: A

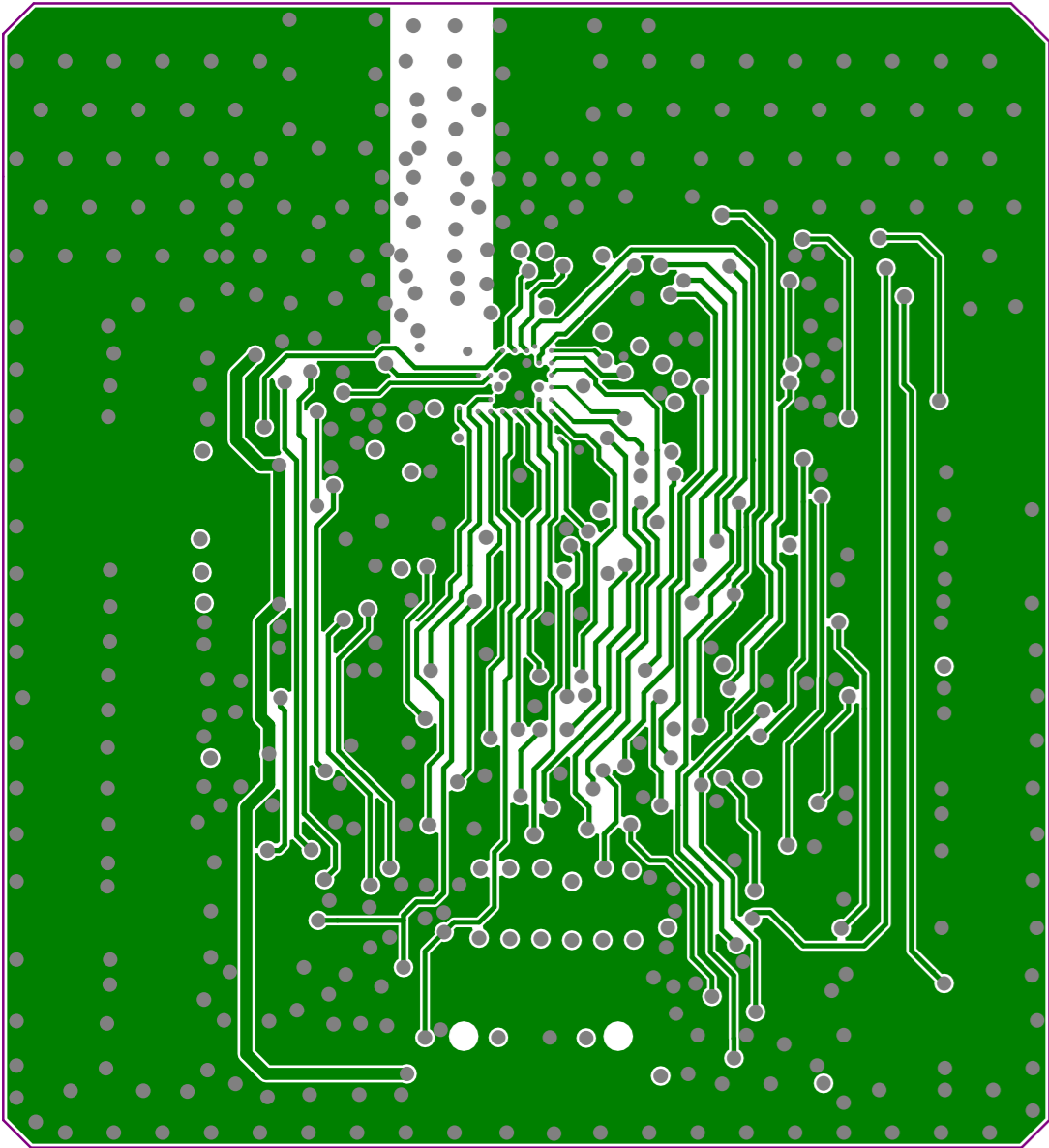
The ST logo, consisting of the letters 'ST' in a bold, italicized, sans-serif font, enclosed within a parallelogram border. A registered trademark symbol (®) is located to the right of the logo.




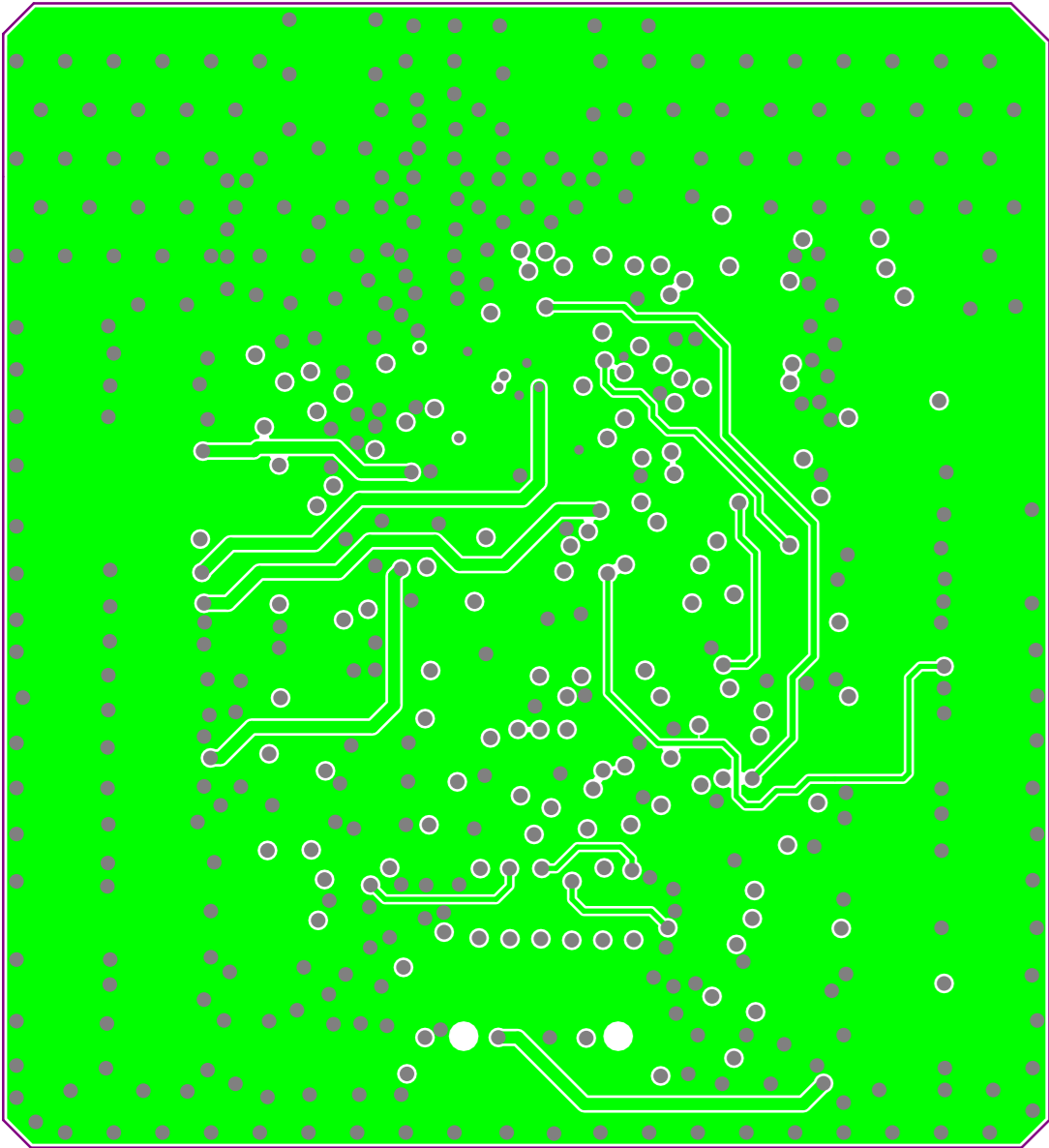
Project: MiniBoard_WBA55_BGA59_SMPS_SMA		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB1807	
Date: 15-Nov-2023	Rev: A	




Project: MiniBoard_WBA55_BGA59_SMPS_SMA		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB1807	
Date: 15-Nov-2023	Rev: A	



Project: MiniBoard_WBA55_BGA59_SMPS_SMA		
Layer: Internal 1	Gerber: .G1	
Variant: [No Variations]	Ref: MB1807	
Date: 15-Nov-2023	Rev: A	



Project: MiniBoard_WBA55_BGA59_SMPS_SMA		
Layer: Internal 2	Gerber: .G2	
Variant: [No Variations]	Ref: MB1807	
Date: 15-Nov-2023	Rev: A	

Project: MiniBoard_WBA55_BGA59_SMPS_SMA

Layer: Bottom Layer

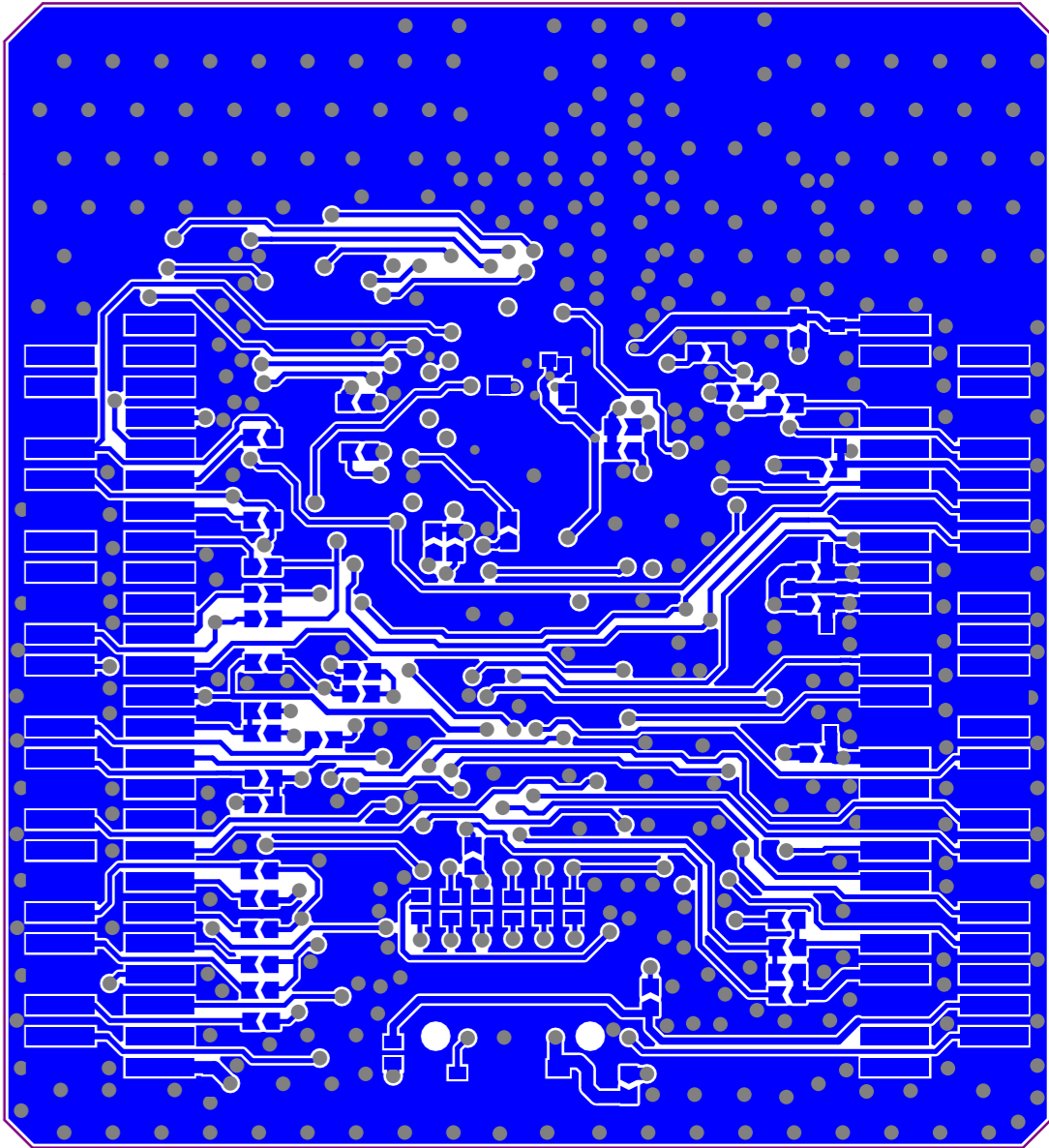
Gerber:.GBL


Variant: [No Variations]

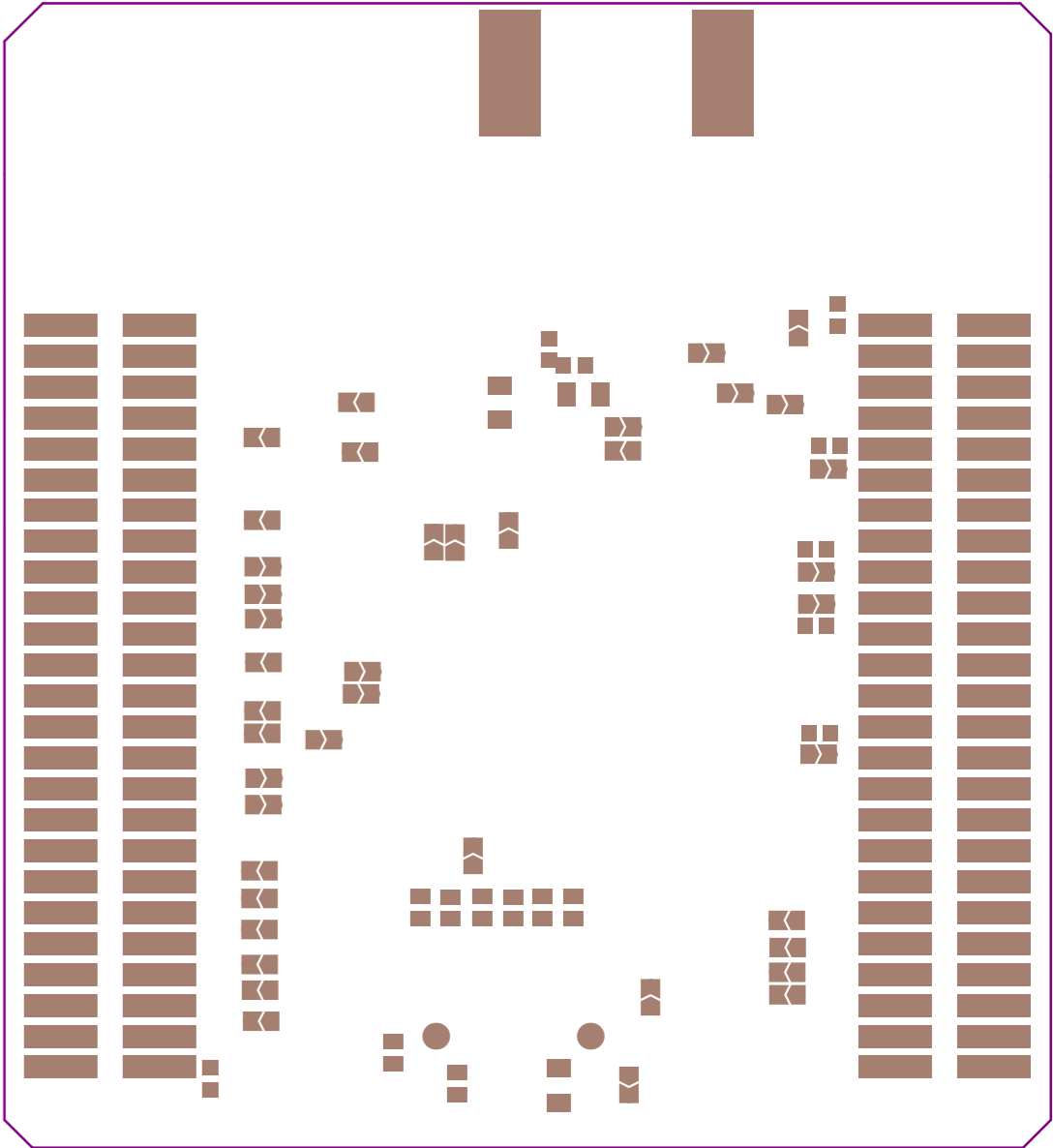
Ref: MB1807


Date: 15-Nov-2023

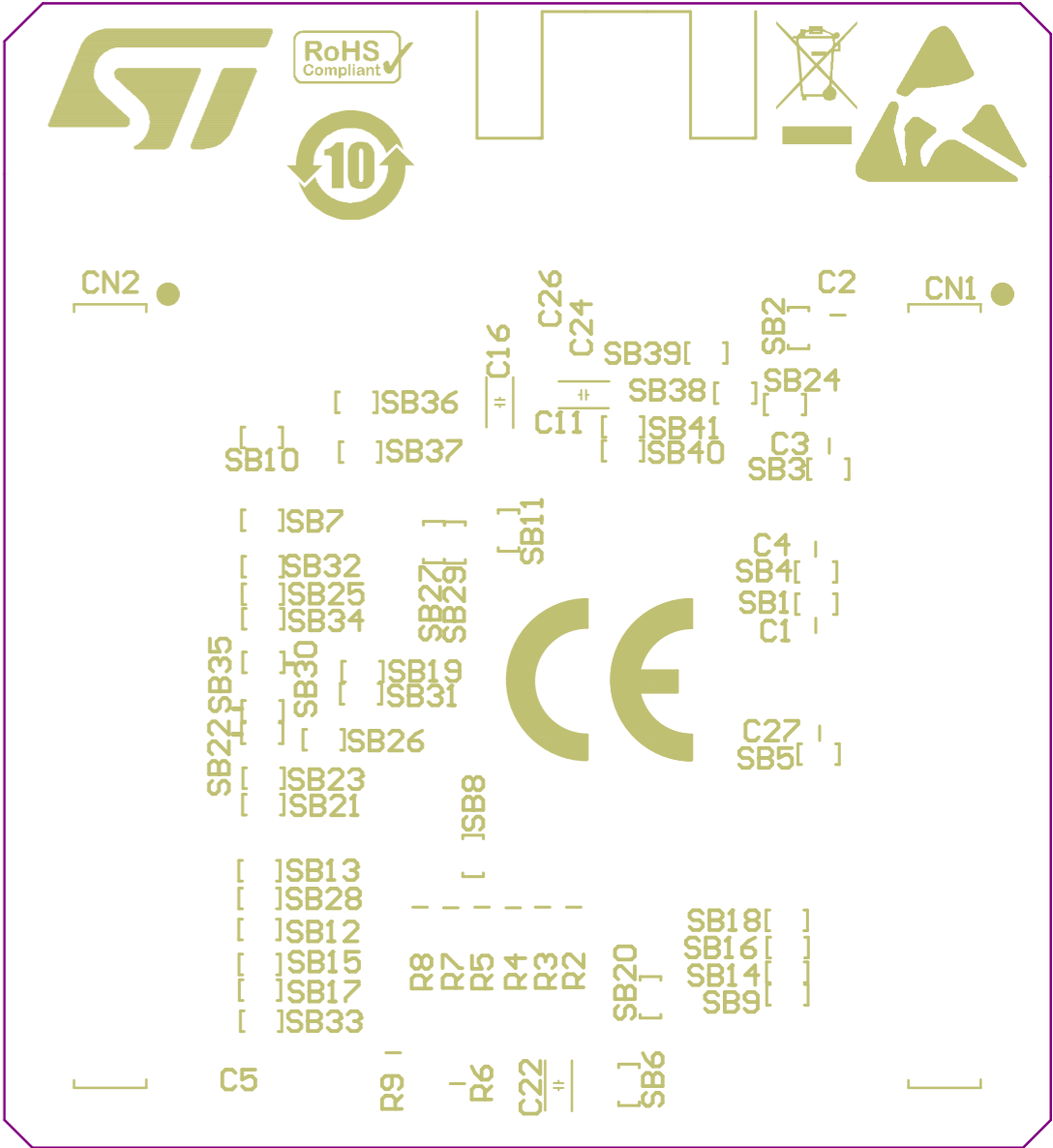
Rev: A



Project: MiniBoard_WBA55_BGA59_SMPS_SMA		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB1807	
Date: 15-Nov-2023	Rev: A	



Project: MiniBoard_WBA55_BGA59_SMPS_SMA		
Layer: Bottom Overlay	Gerber:.GBO	
Variant: [No Variations]	Ref: MB1807	
Date: 15-Nov-2023	Rev: A	



IMPEDANCE TABLE					
LAYER	TRACE	SPACING	IMPEDANCE (Single ended)	IMPEDANCE (Differentiel)	TOL.
TOP	17.716	5.118	50 ohm	NA	+/- 10%

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☒ TG-170

☐ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

☐ IMPEDANCE CONTROL :

☐ NO

☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :




PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

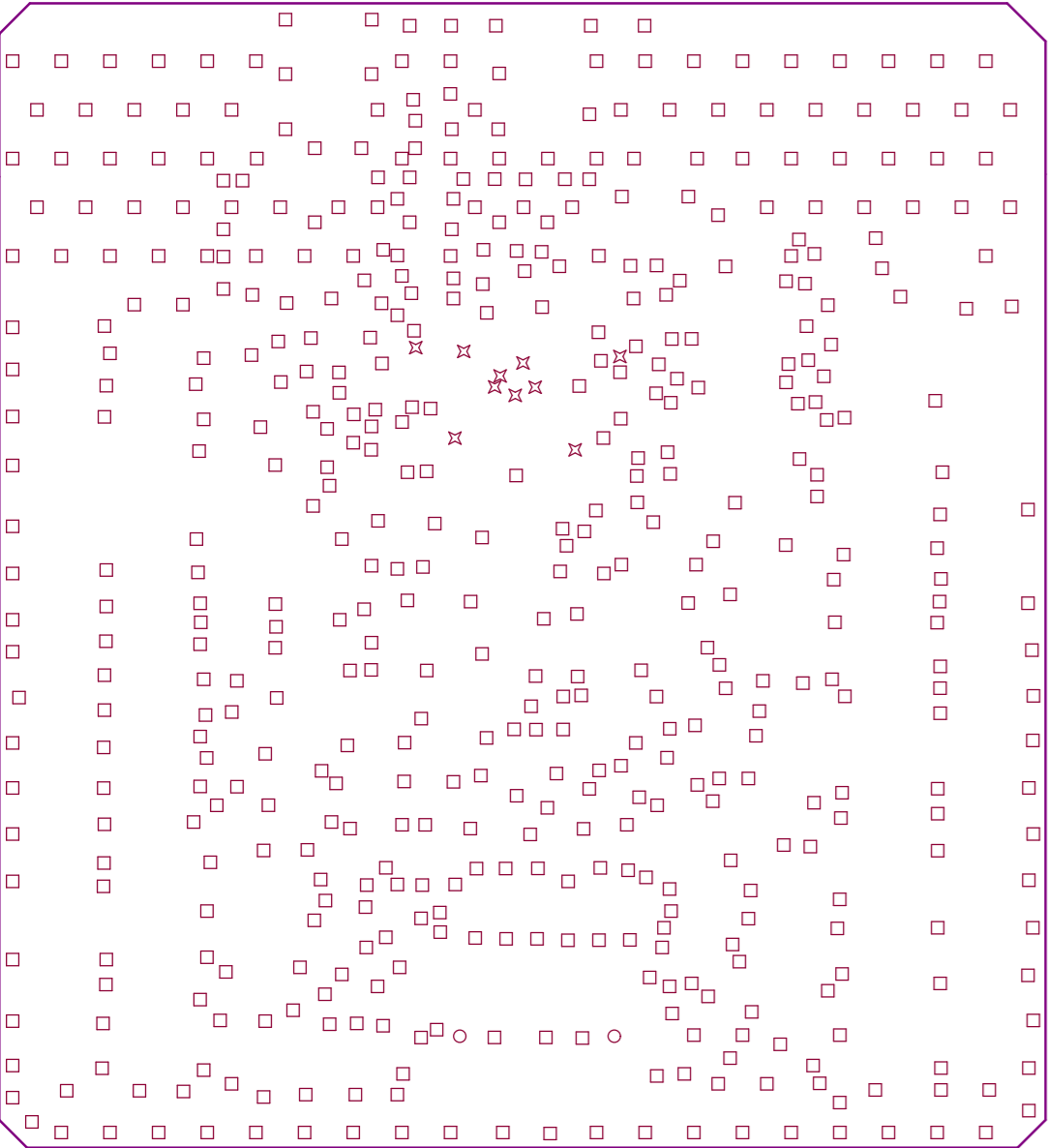
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

☐ STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,70mil	4.2	
1	Top Layer		1,60mil		
	Dielectric 1	FR-4	3,00mil	3.7	
2	Internal 1		1,20mil		
	Dielectric 3		50,00mil	4.5	
3	Internal 2		1,20mil		
	Dielectric 2		3,00mil	3.7	
4	Bottom Layer		1,60mil		
	Bottom Solder	Solder Resist	0,70mil	4.2	
	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
	2	39,37mil (1,00mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn100m105p-1				-	-
	10	7,87mil (0,20mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)				-	-
	517	11,81mil (0,30mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	(Mixed)				-	-
	529 Total												



Project: MiniBoard_WBA55_BGA59_SMPS_SMA

Layer: **Drill Drawing**

Variant: [No Variations]

Date: 15-Nov-2023

Gerber: **.DRL**

Ref: MB1807

Rev: A

